

L Number	Hits	Search Text	DB	Time stamp
1	2	4710732.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 13:25
2	2	6025951.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 13:25
3	2	6059250.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 13:26
4	2	5159225.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 13:26
5	2	5469302.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 13:26
6	2	5506720.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 13:27
7	2	5696618.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 13:27
8	2	5719073.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 13:28
9	2	5846849.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 13:28
-	1157688	mirror or reflect\$6 or micromirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 10:41
-	393398	post	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 10:42
-	1131566	table	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 10:46
-	5334011	flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 10:59

-	66457	trench\$5 or moat\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:16
-	63784	mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:00
-	6806042	flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable or pivot\$6 or tilt\$6 or rotat\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 17:20
-	6932	DMD or (deform\$6 with mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:03
-	61066	degree\$4 adj3 freedom	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:03
-	3295936	actua\$6 or forc\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:20
-	1445932	silicon or Si	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 11:47
-	67205	(silicon or Si) with crystal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 11:48
-	2063993	conduct\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:10
-	1598832	electrostatic or electromagnetic or piezoelectric or thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 17:22
-	404359	etch\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:15
-	1210749	(mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:18
-	6707540	(flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:20
-	1414687	post or table	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:17

-	210795	((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with (post or table)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:21
-	377	post with (trench\$5 or moat\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:24
-	34671	((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and ((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with (post or table))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:45
-	5812	((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and ((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with (post or table))) and (silicon or Si)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:47
-	3688	((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and ((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with (post or table))) and (silicon or Si)) and conduct\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:47
-	1526	((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and ((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with (post or table))) and (silicon or Si)) and conduct\$6) and etch\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:48
-	1182	((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and ((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with (post or table))) and (silicon or Si)) and conduct\$6) and etch\$6) and (electrostatic or electromagnetic or piezoelectric or thermal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:48
-	280525	hinge	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:34

-	499390	array	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:39
-	19809	359/196-324.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:42
-	654685	post or hinge	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:42
-	1660633	(post or hinge) or table	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:43
-	290754	((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with ((post or hinge) or table)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:46
-	41903	((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and ((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with ((post or hinge) or table))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:46
-	6421	((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and (((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with ((post or hinge) or table))) and (silicon or Si)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:47
-	4079	((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and (((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with ((post or hinge) or table))) and (silicon or Si)) and conduct\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:48
-	1710	((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and ((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with ((post or hinge) or table))) and (silicon or Si)) and conduct\$6) and etch\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:48

-	1356	(((((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and (((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with ((post or hinge) or table))) and (silicon or Si)) and conduct\$6) and etch\$6) and (electrostatic or electromagnetic or piezoelectric or thermal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:49
-	67	array and (359/196-324.ccls. and ((((((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and (((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with ((post or hinge) or table))) and (silicon or Si)) and conduct\$6) and etch\$6) and (electrostatic or electromagnetic or piezoelectric or thermal)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:50
-	80	359/196-324.ccls. and ((((((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and (((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with ((post or hinge) or table))) and (silicon or Si)) and conduct\$6) and etch\$6) and (electrostatic or electromagnetic or piezoelectric or thermal)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 11:51
-	10	(US-5469302-\$ or US-4710732-\$ or US-6396619-\$ or US-6323982-\$ or US-6204085-\$ or US-6123985-\$ or US-6031657-\$ or US-6025951-\$ or US-5991066-\$).did. or (US-20020054424-\$).did.	USPAT; US-PGPUB	2002/12/16 13:08
-	1	5469302.pn. and (359/196-324.ccls. and ((((((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and (((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with ((post or hinge) or table))) and (silicon or Si)) and conduct\$6) and etch\$6) and (electrostatic or electromagnetic or piezoelectric or thermal)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 13:20

-	0	5159225.pn. and (359/196-324.ccls. and ((((((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and (((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable) or (degree\$4 adj3 freedom) or (actua\$6 or forc\$6)) with ((post or hinge) or table))) and (silicon or Si)) and conduct\$6) and etch\$6) and (electrostatic or electromagnetic or piezoelectric or thermal)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/16 13:21
-	2	5159225.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 17:19
-	2	5159225.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:01
-	2	5469302.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:02
-	195983	(flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable or pivot\$6 or tilt\$6 or rotat\$6) with (post or hinge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:02
-	166317	(flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable or pivot\$6 or tilt\$6 or rotat\$6) with (table)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:02
-	3297783	actua\$6 or forc\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:02
-	226770	electrostatic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:27
-	371418	electromagnetic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:27
-	135151	piezoelectric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:28
-	978577	thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:28
-	39636	(actua\$6 or forc\$6) with thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:04

-	24226	(actua\$6 or forc\$6) with piezoelectric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:04
-	53434	(actua\$6 or forc\$6) with electromagnetic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:04
-	25526	(actua\$6 or forc\$6) with electrostatic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:04
-	2	5469302.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:02
-	195983	(flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable or pivot\$6 or tilt\$6 or rotat\$6) with (post or hinge)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:23
-	166317	(flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable or pivot\$6 or tilt\$6 or rotat\$6) with (table)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:03
-	3297783	actua\$6 or forc\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:03
-	226770	electrostatic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:03
-	371418	electromagnetic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:03
-	135151	piezoelectric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:03
-	978577	thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:04
-	39636	(actua\$6 or forc\$6) with thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:04
-	24226	(actua\$6 or forc\$6) with piezoelectric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:04
-	53434	(actua\$6 or forc\$6) with electromagnetic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:04

-	25526	(actua\$6 or forc\$6) with electrostatic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:04
-	2	5159225.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/17 18:06
-	21	("3507984" "3510571" "3748504" "3760096" "4441791" "4553061" "4566935" "4571603" "4615595" "4633118" "4638309" "4680579" "4705361" "4710732" "4736132" "4856863" "4859012" "4933592" "4944580" "4956619" "5028939").PN.	USPAT	2002/12/17 18:07
-	30	5159225.URPN.	USPAT	2002/12/17 18:11
-	30	5159225.URPN.	USPAT	2002/12/17 19:04
-	1446527	silicon or Si	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 11:48
-	67263	(silicon or Si) with crystal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 11:49
-	229862	(silicon or Si) with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 11:53
-	19	(US-6396619-\$ or US-6323982-\$ or US-6204085-\$ or US-6123985-\$ or US-6031657-\$ or US-6025951-\$ or US-5991066-\$ or US-5469302-\$ or US-4710732-\$ or US-5552923-\$ or US-5579179-\$ or US-5506720-\$ or US-4933592-\$ or US-6059250-\$ or US-5760947-\$ or US-5696618-\$ or US-5631764-\$ or US-5585956-\$).did. or (US-20020054424-\$).did.	USPAT; US-PGPUB	2002/12/18 11:54
-	1	((silicon or Si) with crystal) and ((US-6396619-\$ or US-6323982-\$ or US-6204085-\$ or US-6123985-\$ or US-6031657-\$ or US-6025951-\$ or US-5991066-\$ or US-5469302-\$ or US-4710732-\$ or US-5552923-\$ or US-5579179-\$ or US-5506720-\$ or US-4933592-\$ or US-6059250-\$ or US-5760947-\$ or US-5696618-\$ or US-5631764-\$ or US-5585956-\$).did. or (US-20020054424-\$).did.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 11:55
-	11	((silicon or Si) with substrate) and ((US-6396619-\$ or US-6323982-\$ or US-6204085-\$ or US-6123985-\$ or US-6031657-\$ or US-6025951-\$ or US-5991066-\$ or US-5469302-\$ or US-4710732-\$ or US-5552923-\$ or US-5579179-\$ or US-5506720-\$ or US-4933592-\$ or US-6059250-\$ or US-5760947-\$ or US-5696618-\$ or US-5631764-\$ or US-5585956-\$).did. or (US-20020054424-\$).did.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:13

-	268791	((silicon or Si) with crystal) or ((silicon or Si) with substrate) or ((silicon or Si) with slab) or ((silicon or Si) with bulk)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:15
-	40606	etch\$6 with (((silicon or Si) with crystal) or ((silicon or Si) with substrate) or ((silicon or Si) with slab) or ((silicon or Si) with bulk))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:16
-	66539	trench\$5 or moat\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:17
-	1415861	post or table	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:17
-	669	(trench\$5 or moat\$5) with (post or table)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:18
-	164	(etch\$6 with (((silicon or Si) with crystal) or ((silicon or Si) with substrate) or ((silicon or Si) with slab) or ((silicon or Si) with bulk))) and ((trench\$5 or moat\$5) with (post or table))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:18
-	1211623	(mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:20
-	63	((etch\$6 with (((silicon or Si) with crystal) or ((silicon or Si) with substrate) or ((silicon or Si) with slab) or ((silicon or Si) with bulk))) and ((trench\$5 or moat\$5) with (post or table))) and ((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:20
-	3297783	actua\$6 or forc\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:21
-	6808228	(flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or positionable or pivot\$6 or tilt\$6 or rotat\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:25
-	226770	electrostatic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:27
-	371418	electromagnetic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:27
-	135151	piezoelectric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:28

-	978577	thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:28
-	1599665	(electrostatic) or (electromagnetic) or (piezoelectric) or thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:36
-	28	((etch\$6 with (((silicon or Si) with crystal) or ((silicon or Si) with substrate) or ((silicon or Si) with slab) or ((silicon or Si) with bulk))) and ((trench\$5 or moat\$5) with (post or table))) and ((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror)))) and (actua\$6 or forc\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:36
-	54	((etch\$6 with (((silicon or Si) with crystal) or ((silicon or Si) with substrate) or ((silicon or Si) with slab) or ((silicon or Si) with bulk))) and ((trench\$5 or moat\$5) with (post or table))) and ((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror)))) and ((electrostatic) or (electromagnetic) or (piezoelectric) or thermal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:36
-	56	((((etch\$6 with (((silicon or Si) with crystal) or ((silicon or Si) with substrate) or ((silicon or Si) with slab) or ((silicon or Si) with bulk))) and ((trench\$5 or moat\$5) with (post or table))) and ((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror)))) and (actua\$6 or forc\$6)) or (((etch\$6 with (((silicon or Si) with crystal) or ((silicon or Si) with substrate) or ((silicon or Si) with slab) or ((silicon or Si) with bulk))) and ((trench\$5 or moat\$5) with (post or table))) and ((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror)))) and ((electrostatic) or (electromagnetic) or (piezoelectric) or thermal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 13:37

-	37	((flex\$6 or mov\$8 or pliant or bend\$6 or elasti\$6 or positioning or postionable or pivot\$6 or tilt\$6 or rotat\$6)) and (((etch\$6 with ((silicon or Si) with crystal) or ((silicon or Si) with substrate) or ((silicon or Si) with slab) or ((silicon or Si) with bulk))) and ((trench\$5 or moat\$5) with (post or table))) and ((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and (actua\$6 or forc\$6)) or (((etch\$6 with ((silicon or Si) with crystal) or ((silicon or Si) with substrate) or ((silicon or Si) with slab) or ((silicon or Si) with bulk))) and ((trench\$5 or moat\$5) with (post or table))) and ((mirror or reflect\$6 or micromirror) or (mems or (micro\$3electro\$6) or (micro\$3 with electromechan\$5)) or (DMD or (deform\$6 with mirror))) and ((electrostatic) or (electromagnetic) or (piezoelectric) or thermal)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 16:19
-	2	5719073.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 13:24
-	2	5846849.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/18 16:20